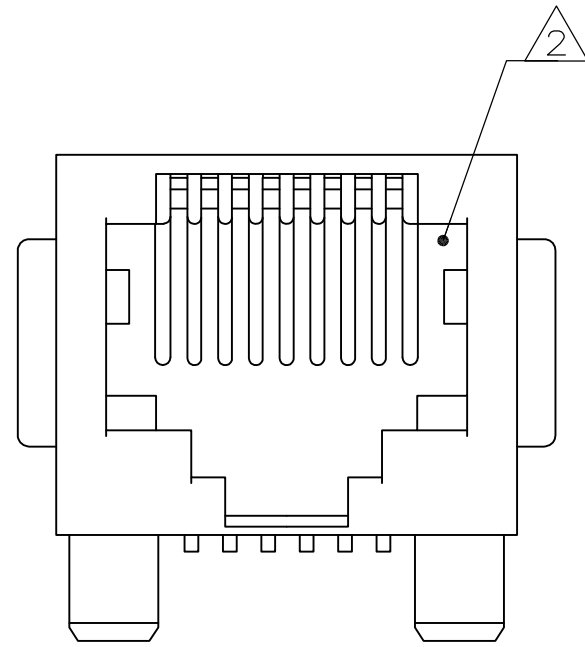
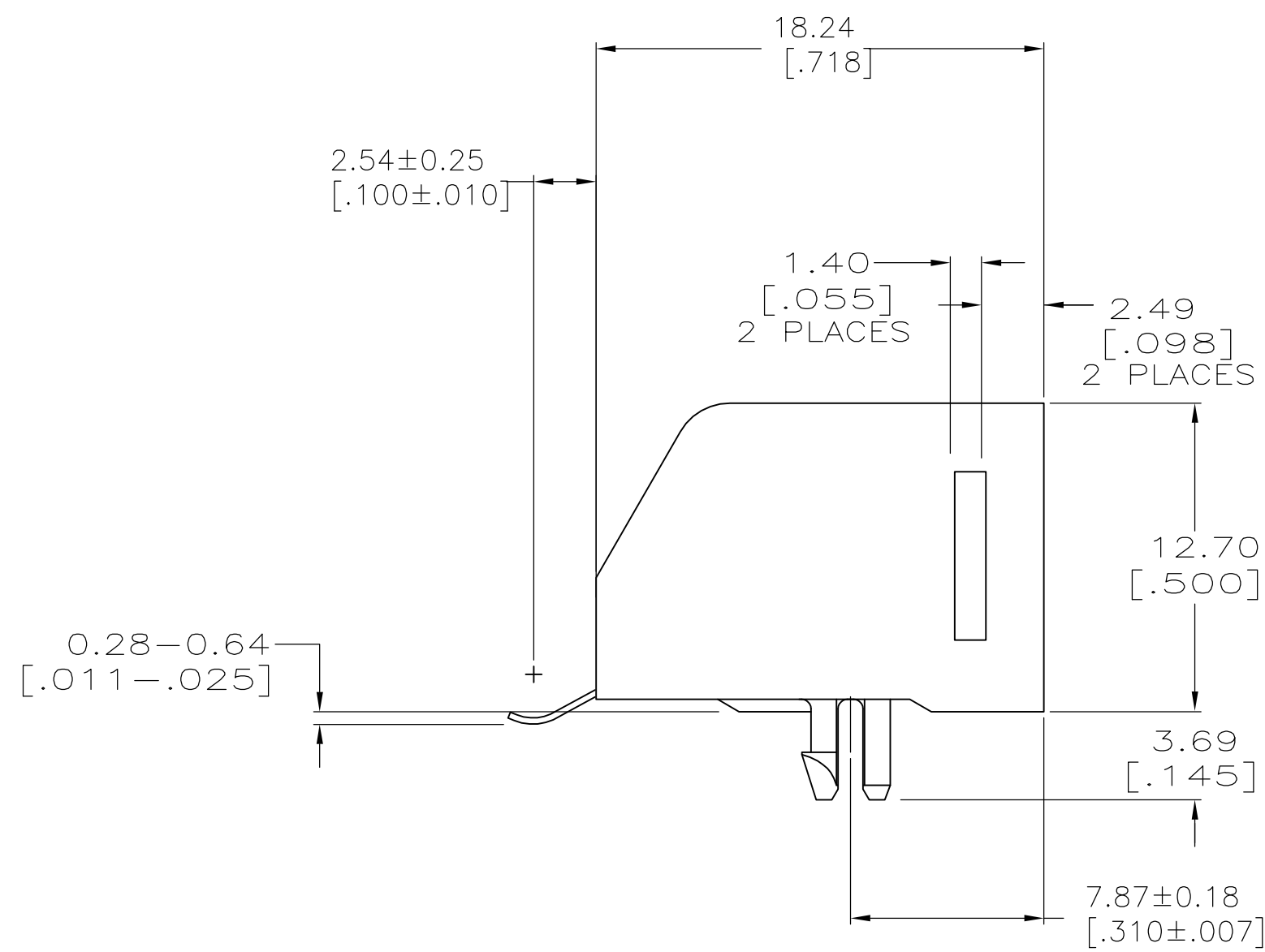


D

C

B

A

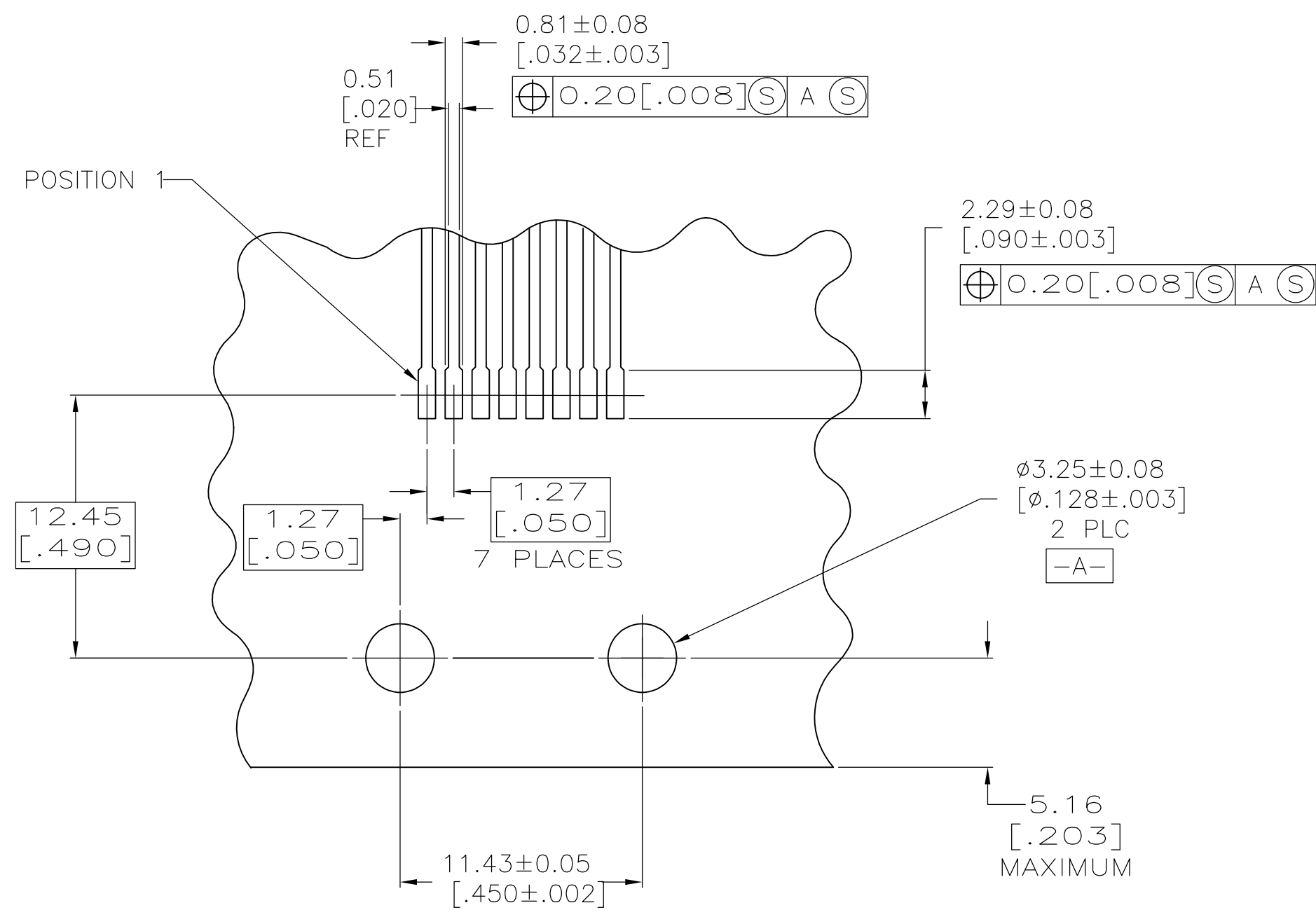
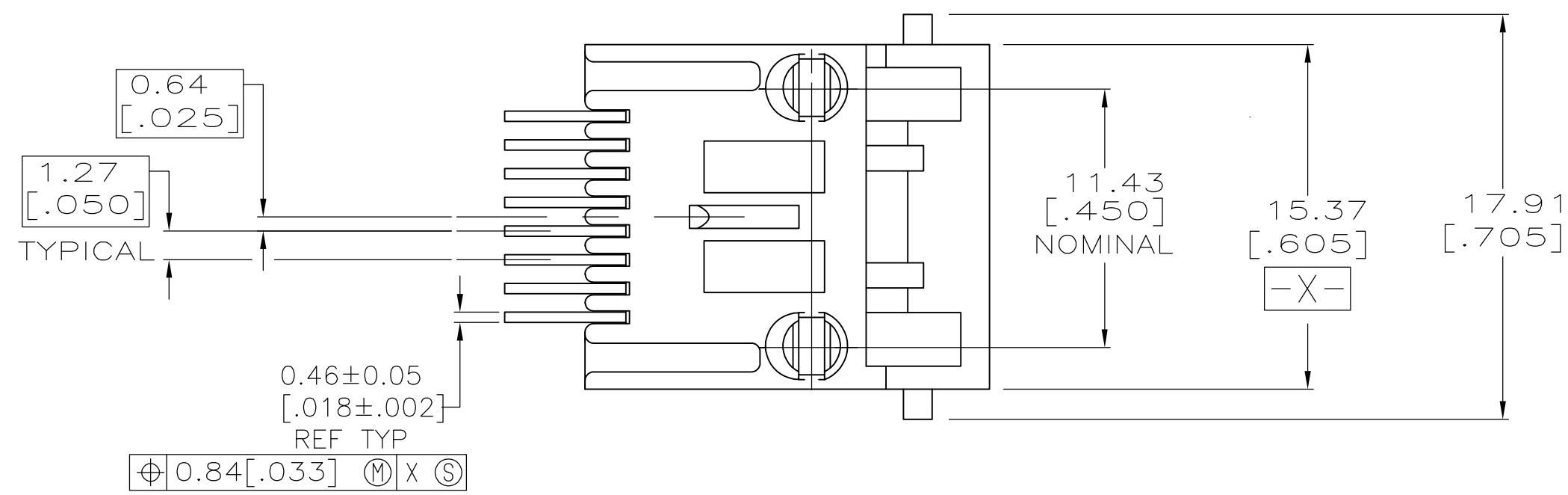


1. MATERIAL: HOUSING — HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK
TERMINAL — 0.36 [.014] THICK PHOS-BRONZE PLATE WITH 1.27μm [.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81μm [.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27μm [.000050] MINIMUM THICK NICKEL UNDERPLATE.

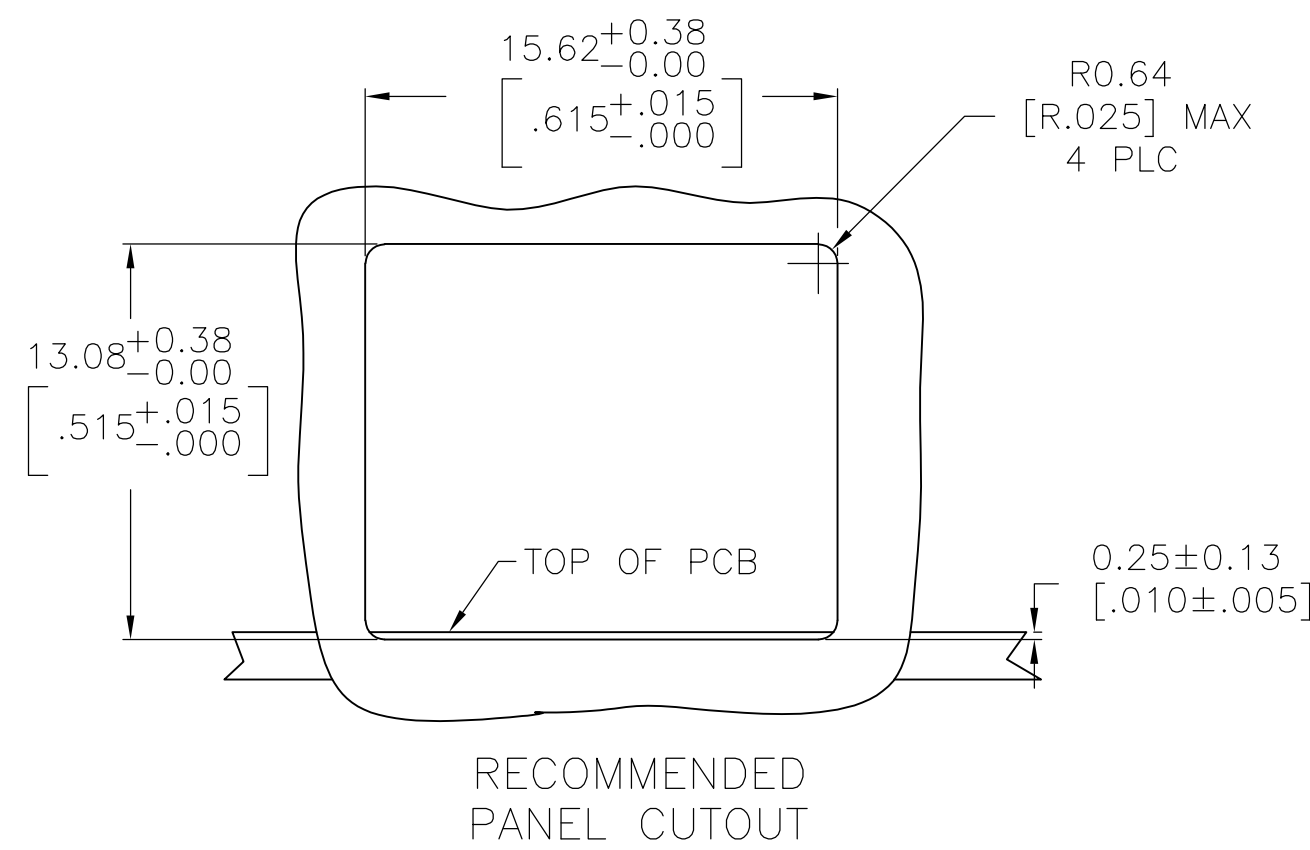
△ CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.

3. ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.

4. SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [.062±.005] THICK PRINTED CIRCUIT BOARD.



RECOMMENDED PRINTED CIRCUIT BOARD
COMPONENT SIDE



D

C

B

A

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN G. ATTADIA — 08/JUN/2005 CHK J. WESTMAN — 08/JUN/2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608			
DIMENSIONS: mm [INCHES]		APVD S. FLICKINGER — 08/JUN/2005	NAME			
		MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, WITH PANEL STOPS				
		PRODUCT SPEC 108-1163				
		APPLICATION SPEC 114-6040				
		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± - ± -				
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT —	SIZE A1	CAGE CODE 00779	DRAWING NO 5555248	RESTRICTED TO —
		CUSTOMER DRAWING		SCALE 4:1	SHEET 1 OF 1	REV B